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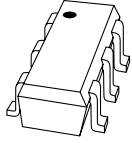
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Kind regards,

Team Nexperia



# PUMX2

## NPN/NPN general-purpose double transistors

Rev. 02 — 17 November 2009

Product data sheet

## 1. Product profile

### 1.1 General description

NPN/NPN general-purpose double transistors in a small SOT363 (SC-88) Surface Mounted Device (SMD) plastic package.

### 1.2 Features

- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs

### 1.3 Applications

- General-purpose switching and amplification

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$V_{CEO}$	collector-emitter voltage	open base	-	-	50	V
$I_C$	collector current		-	-	150	mA
$h_{FE}$	DC current gain	$V_{CE} = 6\text{ V}; I_C = 1\text{ mA}$	120	250	560	

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	emitter TR1		
2	emitter TR2		
3	base TR2		
4	collector TR2		
5	base TR1		
6	collector TR1		

### 3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
PUMX2	SC-88	plastic surface mounted package; 6 leads	SOT363

### 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
PUMX2	Z1*

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

### 5. Limiting values

Table 5. Limiting values

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per transistor</b>					
$V_{CBO}$	collector-base voltage	open emitter	-	60	V
$V_{CEO}$	collector-emitter voltage	open base	-	50	V
$V_{EBO}$	emitter-base voltage	open collector	-	7	V
$I_C$	collector current		-	150	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	200	mA
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]	180	mW
<b>Per device</b>					
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]	300	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	694	K/W
<b>Per device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	417	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

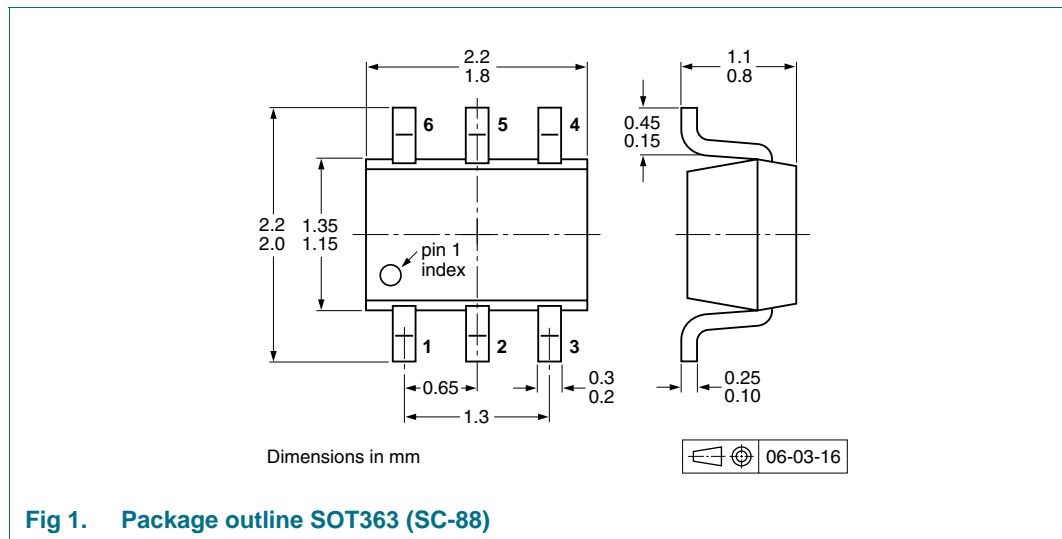
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 60\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
		$V_{CB} = 60\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	50	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 7\text{ V}; I_C = 0\text{ A}$	-	-	100	nA
$h_{FE}$	DC current gain	$V_{CE} = 6\text{ V}; I_C = 1\text{ mA}$	120	250	560	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 50\text{ mA}; I_B = 5\text{ mA}$	-	-	250	mV
$f_T$	transition frequency	$V_{CE} = 12\text{ V}; I_E = 2\text{ mA}; f = 100\text{ MHz}$	100	-	-	MHz
$C_c$	collector capacitance	$V_{CB} = 12\text{ V}; I_E = I_e = 0\text{ A}; f = 1\text{ MHz}$	-	-	3	pF

## 8. Package outline



## 9. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PUMX2	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2] -115	-135
		4 mm pitch, 8 mm tape and reel; T2	[3] -125	-165

[1] For further information and the availability of packing methods, see [Section 13](#).

[2] T1: normal taping

[3] T2: reverse taping

10. Soldering

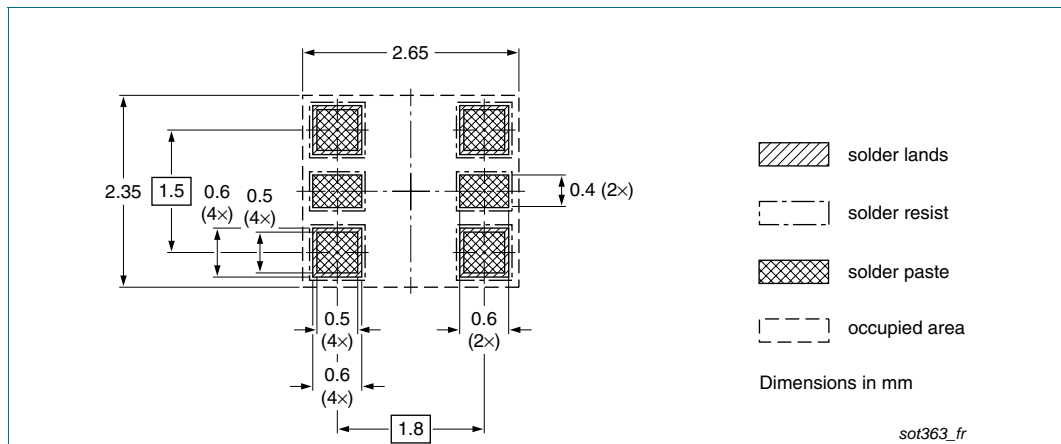


Fig 2. Reflow soldering footprint SOT363 (SC-88)

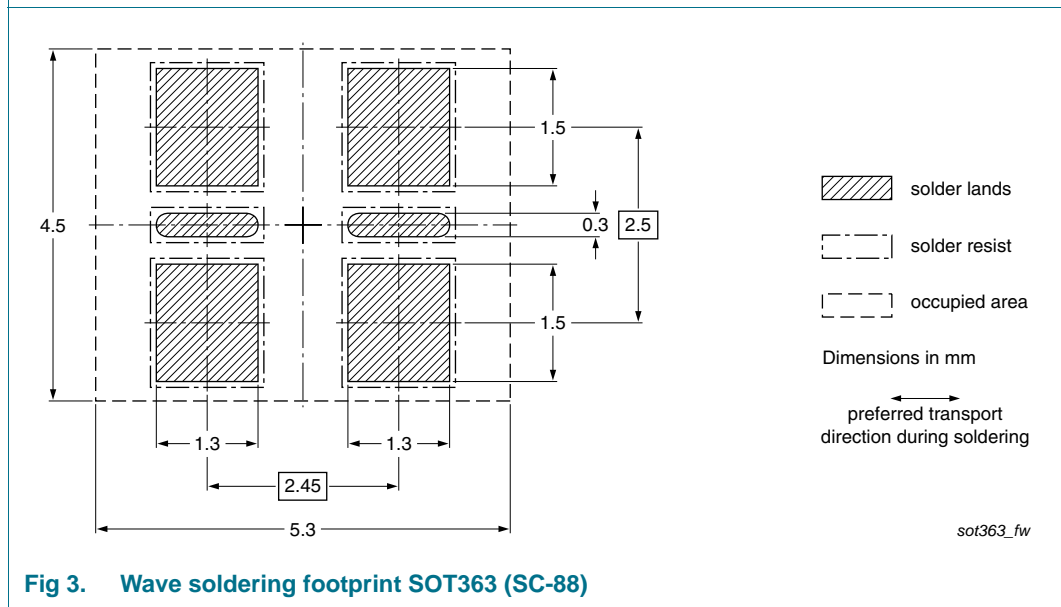


Fig 3. Wave soldering footprint SOT363 (SC-88)

## 11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PUMX2_2	20091117	Product data sheet	-	PUMX2_1
Modifications:		<ul style="list-style-type: none"><li>• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li><li>• <a href="#">Figure 1 “Package outline SOT363 (SC-88)”</a>: updated</li><li>• <a href="#">Figure 2 “Reflow soldering footprint SOT363 (SC-88)”</a>: updated</li><li>• <a href="#">Figure 3 “Wave soldering footprint SOT363 (SC-88)”</a>: updated</li></ul>		
PUMX2_1	20051110	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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